

Investor Presentation

January 2024

Disclaimer



This presentation contains forward-looking statements relating to the business, financial performance and earnings of SÜSS MicroTec SE and its subsidiaries and associates.

Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SÜSS MicroTec SE. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements.

SÜSS MicroTec SE does not intend or accept any obligation to publish updates of these forward-looking statements.





- Hidden champion headquartered in Germany with 70+ year track record of innovation and growth
- Key technology provider for semiconductor frontend and advanced backend industry
- Global customer base with largest share of business in Asia
- Strategic partner for global semiconductor
 IDMs and foundries
- Innovator with relevant network to research institutes and universities
- 2025 Target: more than € 400 million revenue and >15% EBIT margin



299 in € million

Sales 2022

446 in € million

Order intake 2022 EBI

11%

EBIT margin 2022

Management Board of SÜSS MicroTec SE









CFO

Dr. Cornelia Ballwiesser

- Finance and Controlling
- Legal and Compliance
- Internal Audit
- Investor Relations
- IT
- ESG

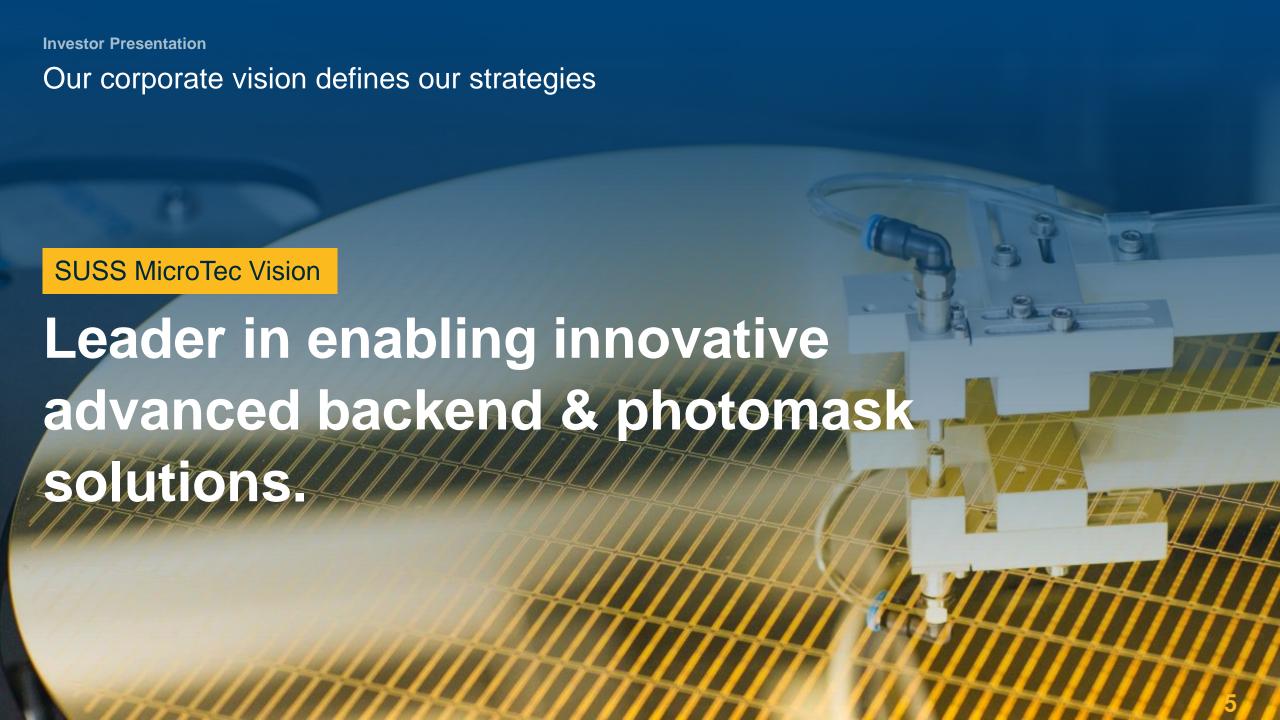
Burkhardt Frick

- Sales and Service
- Strategy
- HR
- Business Units:
 Advanced Backend Solutions,
 Photomask Solutions, MicroOptics

COO

Dr. Thomas Rohe

- R&D
- Purchasing
- Production
- Logistics
- Quality Management
- Product Center
- Facility Management



Our world are the semiconductor frontend and backend process steps



Wafer fabrication

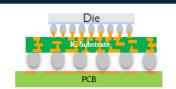


Front-end-of-line Wafer process



- Deposition/coating
- Cleaning
- Patterning/lithography¹
- Etching
- Implantation
- Annealing
- Permanent bonding
- Temporary bonding
- CMP polishing

From middle-of-line to back-end-of-line Advanced packaging



- Deposition/coating
- Cleaning
- Patterning/lithography
- Etching
- Annealing
- CMP polishing
- Permanent bonding
- Temporary bonding
- Wafer-level packaging
- Wafer dicing
- Panel-level packaging

Final packaging



- Mounting
- Wire bonding
- Molding encapsulation
- Trim & forming

Only related to Photomask processing Source: Yole, Lithography and Bonding Equipment for More than Moore 2022

Advanced Backend Solutions as core asset in our product portfolio



Frontend

Segments Photomask Equipment



Advanced backend

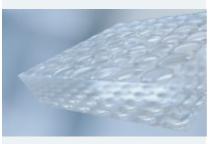
Advanced Backend Solutions¹





Components²

MicroOptics



Products









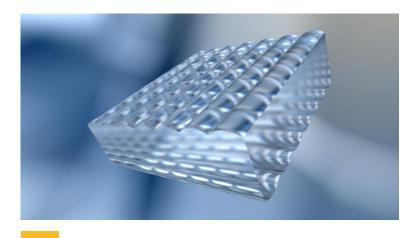




- Business units Lithography and Bonder were merged into the new Advanced Backend Solutions business unit at the end of 2022. We will report in the new structure from the 2023 financial year onwards.
- This business unit belongs no longer to the core business. We signed an agreement to sell the SUSS MicroOptics business to Focuslight Technologies on November 8, 2023.

Signing completed for the sale of MicroOptics business









1

Reasons for divestment

- Limited synergies with core semiconductor equipment businesses (R&D, manufacturing, distribution)
- Further growth requires higher investment in automation and scaling
- We do not consider ourselves to be experts in targeted automotive business

2

Key facts of transaction

- Type: share deal (acquisition of 100% of SUSS MicroOptics SA shares)
- Transaction volume: € 75.5 million (includes acquisition of all shares and redemption of debt)
- Expected closing: Q1 2024
- Expected extraordinary income before taxes: € 40 to 45 million

3

Buyer's profile: Focuslight

- Listed at Shanghai stock exchange (ISIN: CNE100005XV2)
- ~ 800 employees
- Focus: diode laser components and laser optics
- Experienced in Western Europe through acquisition of German based company LIMO in 2017

Al related opportunity is larger than we initially expected



So far, we received AI related orders for our temporary bonders, debonders and cleaners worth ~ € 100 million.







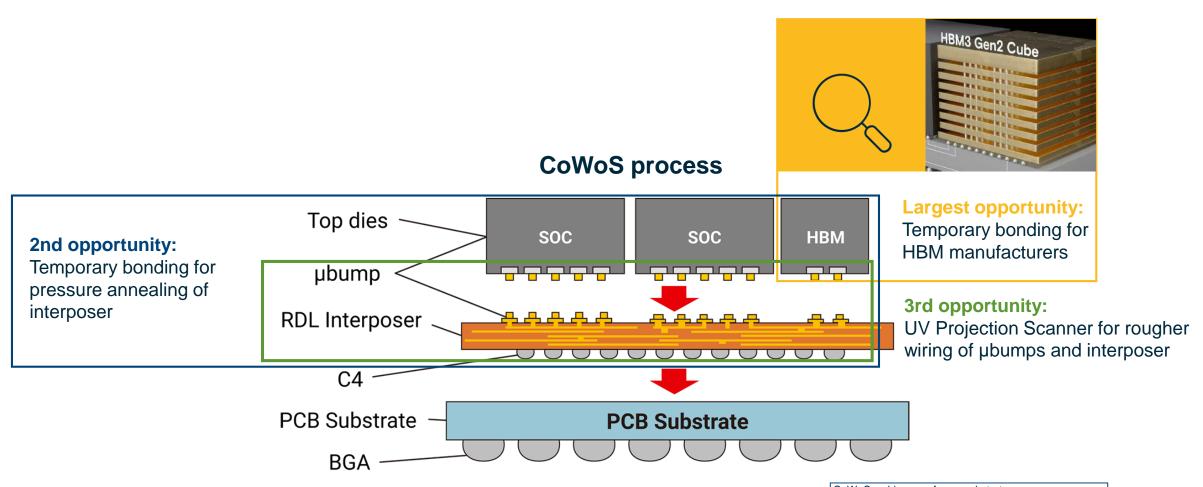




- Demand for our solutions is boosted in particular by dramatic capacity increase at Korean and Taiwanese HBM (high bandwidth memory chip) manufacturers.
- After a first order in June 2023, we received the largest POs in September and October.
- As a result, we achieved the bonder's highest ever order intake in the third quarter of 2023.
- To meet demand, we are qualifying our production site in Hsinchu (Taiwan) to build the XBS300 temporary bonding platform in the future. For this, we are hiring > 50 new employees.

We benefit from the boom in Al





Sources: TSMC, Micron

CoWoS – chip on wafer on substrate

SOC – system on chip

HBM – hogh bandwidth memory

RDL – redistribution layer

C4 – controlled collapse chip connection

PCB – printed circuit board

BGA – ball grid array

Robust order momentum remains, sales deprived by export delays



Financial Results Q3 2023*

281.2

in € million

Order Entry 9M 2023

202.3

in € million

Sales 9M 2023 33.5

in %

Gross profit margin 9M 2023

6.3

in %

EBIT Margin 9M 2023

Guidance adjustment on October 25, 2023 for all three key financial indicators

SÜSS MicroTec

Revised guidance due to delayed deliveries to China and unsatisfying margins

Our adjusted guidance 2023





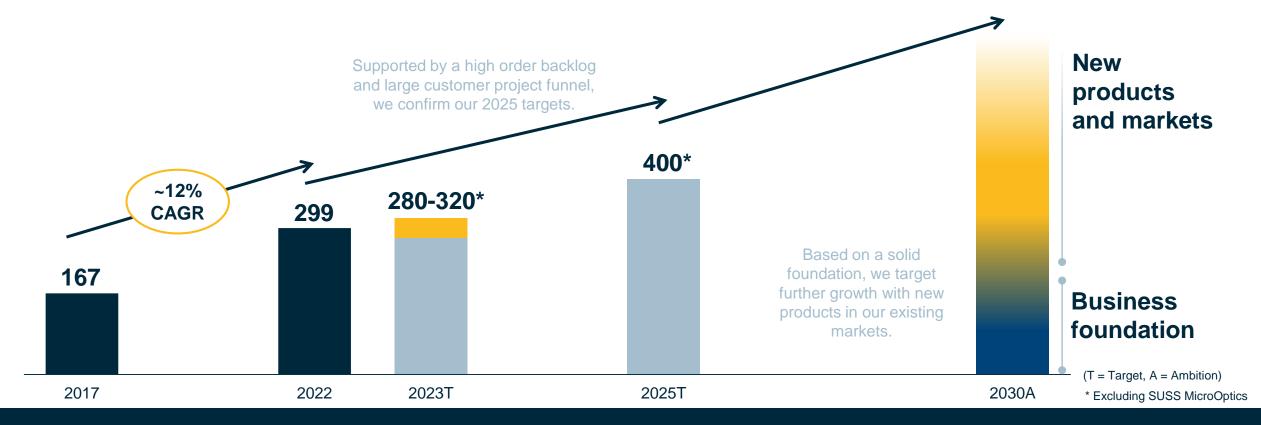


¹⁾ Without SUSS MicroOptics

²⁾ Including one-off effects of € 3.1 million. Operating EBIT margin thus accounted to 9.9%.

SUSS MicroTec

Based on our business foundation we see further potential beyond



Major growth drivers 2023

 Converting high order backlog in Photomask Solutions and Bonder business into sales growth

Major growth drivers 2024/2025

- Bonding (especially with regard to Aldriven demand for temporary bonders)
- Photomask Solutions

Major growth drivers 2030

- General expected market growth in our core businesses (lithography, bonding, photomask)
- Hybrid Bonding
- Wafer Cleaning

Investor Relations Information

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Financial Calendar 2024

